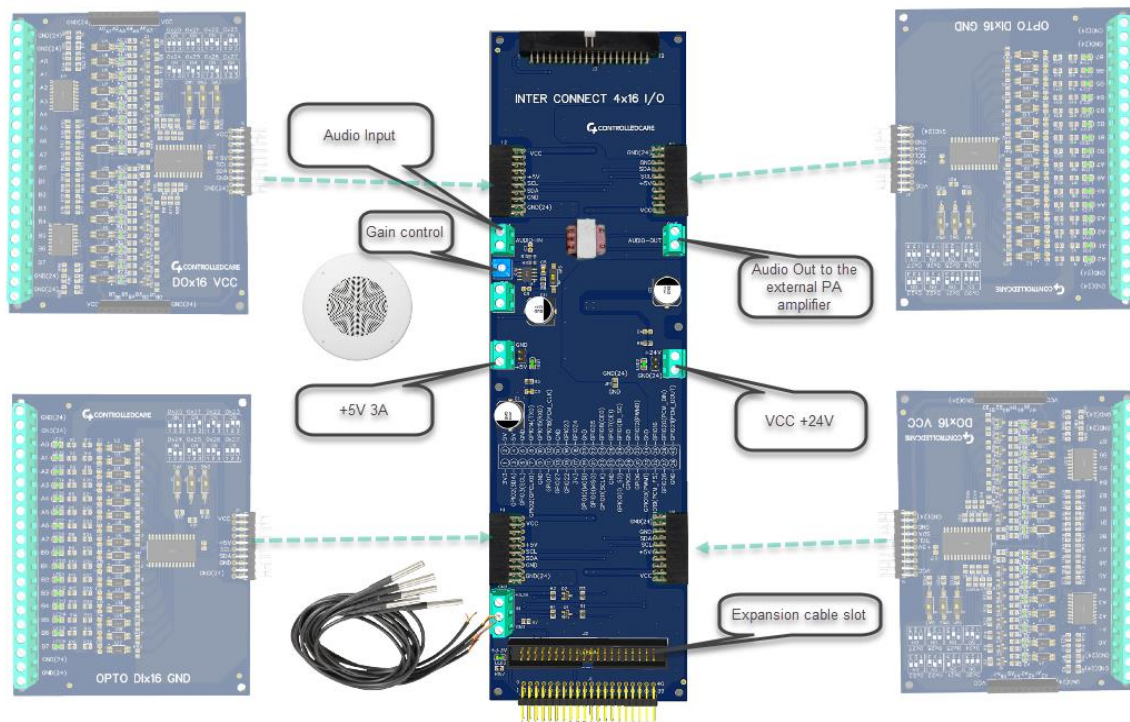
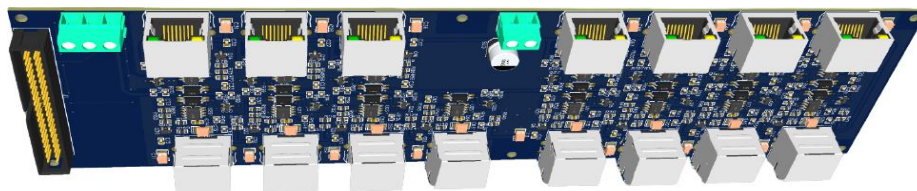


## DIGITAL INTERCONNECT DI+DO Module

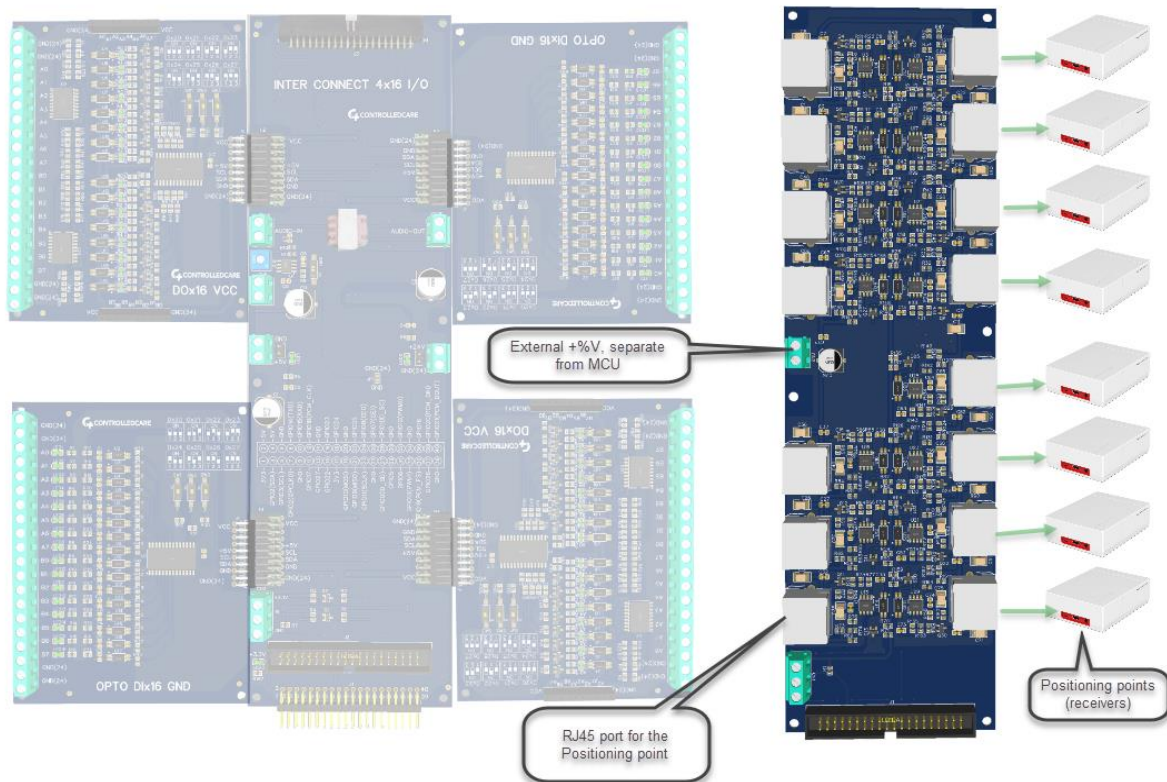
This module is designed to interconnect up to 4 attachable modules, to resolve their addressing, to connect up to 128 temperature sensors, isolate noise loop from MCU audio output, deliver audio to the external PA amplifier, connect a 4~8Ohm speaker and deliver power from external sources.



In the hybrid mode, when the location and positioning is required, on top of this module can be installed addition location board.



Wireless location and positioning module require separate +5V power source, isolated from MCU.  
To this board can be connected up to 15 positioning points, which is more than enough per one floor.



Distance between position points and dedicated port is limited to 750 meters.  
If to use CAT6 cable, then cable run can be longer, but not more than 1200 meters.

External +5V power source must be a separated from the MCU unit, and minimum supply is 1A.

Location module can be used without main interconnect board, when only wireless NCS is required.